



Atty. Dkt. No.: 200335-0037  
U.S. Serial No.; 09/671,084

AMENDMENT RESPONSIVE TO OFFICE ACTION  
(Paper No. 5) MAILED MARCH 22, 2001

Responsive to an Office Action (Paper No. 5) mailed March 22, 2001, please amend the application, as follows:

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*RECEIVED*  
*JUL 30 2001*  
*TC 1700*  
*130101*

IN THE CLAIMS:

3. (Amended) The solder according to claim 1, wherein said solder has a copper dissolution rate of 0.20  $\mu\text{m/sec}$  or less.

4. (Amended) The solder according to claim 1, wherein said solder has a liquidus temperature of 240°C or lower.

5. (Amended) The solder according to claim 1, wherein said solder has a liquidus temperature of 230°C or lower.

11. (Amended) The solder according to claim 9, wherein said solder has a copper dissolution rate of 0.20  $\mu\text{m/sec}$  or less.

12. (Amended) The solder according to claim 9, wherein said solder has a liquidus temperature of 240°C or lower.

13. (Amended) The solder according to claim 9, wherein said solder has a liquidus temperature of 230°C or lower.